

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

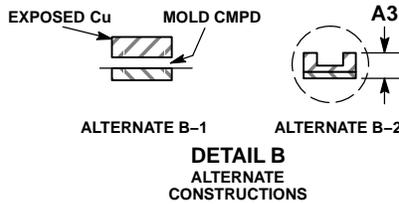
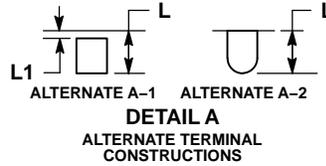
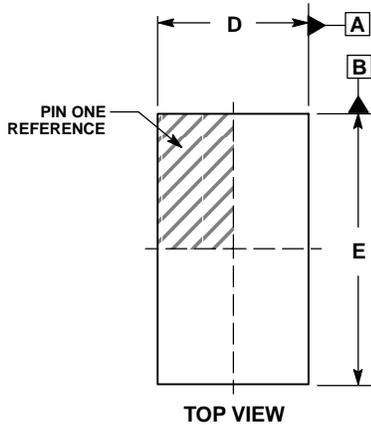
ON Semiconductor®



SCALE 2:1

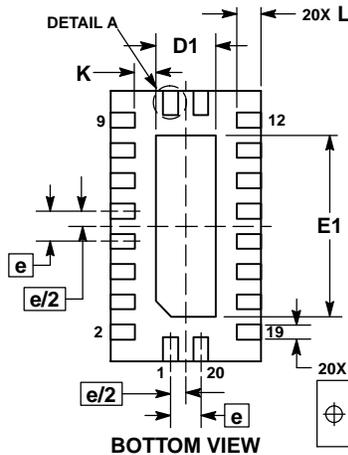
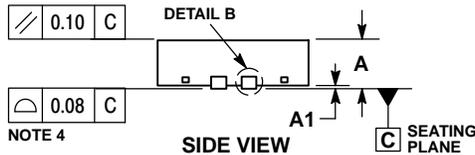
QFN20 2.5x4.5, 0.5P
CASE 485FK
ISSUE O

DATE 08 MAY 2017



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25MM FROM THE TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

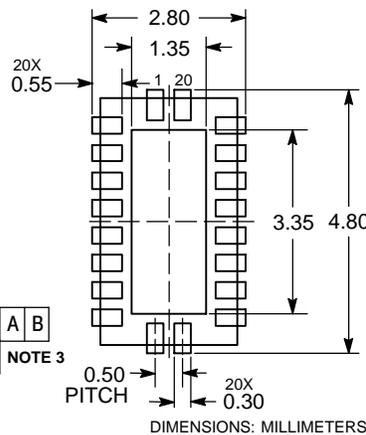
MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	---	---	0.05
A3	0.203 REF		
b	0.20	0.25	0.30
D	2.40	2.50	2.60
D1	0.95	1.05	1.15
E	4.40	4.50	4.60
E1	2.95	3.05	3.15
e	0.50 BSC		
K	0.325 REF		
L	0.30	0.40	0.50
L1	---	---	0.05



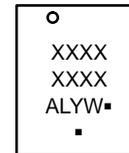
0.10	C	A	B
0.05	C		

NOTE 3

RECOMMENDED SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN20 2.5X4.5, 0.5P	PAGE 1 OF 2

